



## Absolute Maximum Ratings

|                                                                                                           |                |
|-----------------------------------------------------------------------------------------------------------|----------------|
| IN, CS, LX, DIM to GND .....                                                                              | -0.3V to +70V  |
| TEMP_I to GND .....                                                                                       | -0.3V to +6V   |
| PGND to GND .....                                                                                         | -0.3V to +0.3V |
| CS to IN .....                                                                                            | -0.3V to +0.3V |
| Maximum Current into Any Pin<br>(except IN, LX, and PGND).....                                            | 20mA           |
| Continuous Power Dissipation ( $T_A = +70^\circ\text{C}$ )<br>8-Pin SO (derate 7.4mW/°C above +70°C)..... | 588.2mW        |

|                                                                      |                    |
|----------------------------------------------------------------------|--------------------|
| Junction-to-Ambient Thermal Resistance ( $\theta_{JA}$ ) (Note 1)... | 136°C/W            |
| Pin-to-Pin ESD Ratings.....                                          | $\pm 2.5\text{kV}$ |
| Operating Temperature Range                                          |                    |
| 350mA (max) Output Current .....                                     | -40°C to +125°C    |
| 500mA (max) Output Current .....                                     | -40°C to +105°C    |
| Junction Temperature .....                                           | +150°C             |
| Storage Temperature Range .....                                      | -65°C to +150°C    |
| Lead Temperature (soldering, 10s) .....                              | +300°C             |

**Note 1:** Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a four-layer board. For detailed information on package thermal considerations, see [www.maximintegrated.com/thermal-tutorial](http://www.maximintegrated.com/thermal-tutorial).

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

## Electrical Characteristics

( $V_{IN} = +24\text{V}$ ,  $V_{DIM} = V_{IN}$ ,  $T_A = T_J = -40^\circ\text{C}$  to  $+125^\circ\text{C}$ , unless otherwise noted. Typical values are at  $T_A = +25^\circ\text{C}$ .)

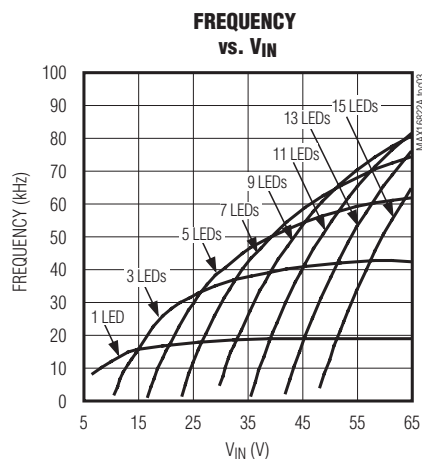
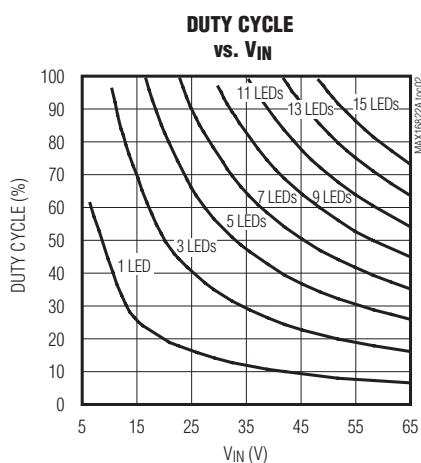
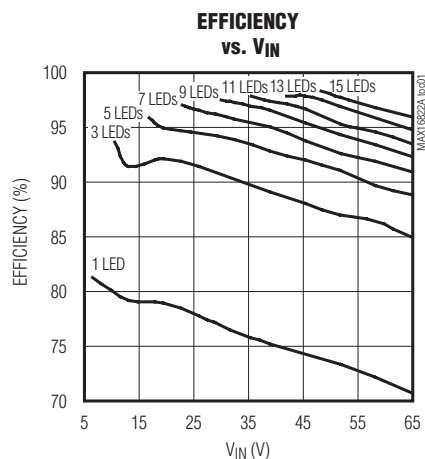
| PARAMETER                          | SYMBOL      | CONDITIONS                                                                               | MIN | TYP  | MAX | UNITS         |
|------------------------------------|-------------|------------------------------------------------------------------------------------------|-----|------|-----|---------------|
| Input-Voltage Range                | $V_{IN}$    |                                                                                          | 6.5 |      | 65  | V             |
| Ground Current                     |             | No switching                                                                             |     | 1.5  |     | mA            |
| Supply Current                     |             | $V_{DIM} < 0.6\text{V}$ , $V_{IN} = 12\text{V}$                                          |     | 350  |     | $\mu\text{A}$ |
| <b>UNDERVOLTAGE LOCKOUT (UVLO)</b> |             |                                                                                          |     |      |     |               |
| Undervoltage Lockout               | UVLO        | $V_{CS} = V_{IN} - 100\text{mV}$ , $V_{IN}$ rising from 4V until $V_{LX} < 0.5V_{IN}$    |     | 6.25 | 6.5 | V             |
|                                    |             | $V_{CS} = V_{IN} - 100\text{mV}$ , $V_{IN}$ falling from 6.5V until $V_{LX} > 0.5V_{IN}$ |     |      | 6   |               |
| Undervoltage-Lockout Hysteresis    |             |                                                                                          |     | 0.5  |     | V             |
| <b>SENSE COMPARATOR</b>            |             |                                                                                          |     |      |     |               |
| Sense Voltage Threshold High       | $V_{SNSHI}$ | MAX16822A, $V_{IN} - V_{CS}$ rising from 140mV until $V_{LX} > 0.5V_{IN}$                | 201 | 210  | 216 | mV            |
|                                    |             | MAX16822B, $V_{IN} - V_{CS}$ rising from 140mV until $V_{LX} > 0.5V_{IN}$                | 218 | 230  | 236 |               |
| Sense Voltage Threshold Low        | $V_{SNSLO}$ | MAX16822A, $V_{IN} - V_{CS}$ falling from 260mV until $V_{LX} < 0.5V_{IN}$               | 185 | 190  | 198 | mV            |
|                                    |             | MAX16822B, $V_{IN} - V_{CS}$ falling from 260mV until $V_{LX} < 0.5V_{IN}$               | 166 | 170  | 180 |               |
| Propagation Delay to Output High   | $t_{DPDH}$  | Falling edge of $V_{IN} - V_{CS}$ from 140mV to 260mV to $V_{LX} > 0.5V_{IN}$            |     | 50   |     | ns            |
| Propagation Delay to Output Low    | $t_{DPDL}$  | Rising edge of $V_{CS} - V_{IN}$ from 260mV to 140mV to $V_{LX} < 0.5V_{IN}$             |     | 50   |     | ns            |
| CS Input Current                   | $I_{CSIN}$  | $V_{IN} - V_{CS} = 200\text{mV}$                                                         |     |      | 3.5 | $\mu\text{A}$ |

## Electrical Characteristics (continued)

(V<sub>IN</sub> = +24V, V<sub>DIM</sub> = V<sub>IN</sub>, T<sub>A</sub> = T<sub>J</sub> = -40°C to +125°C, unless otherwise noted. Typical values are at T<sub>A</sub> = +25°C.)

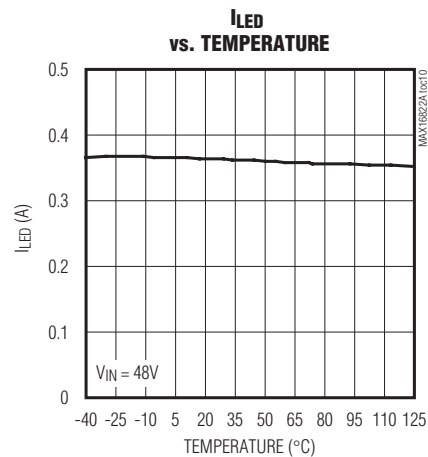
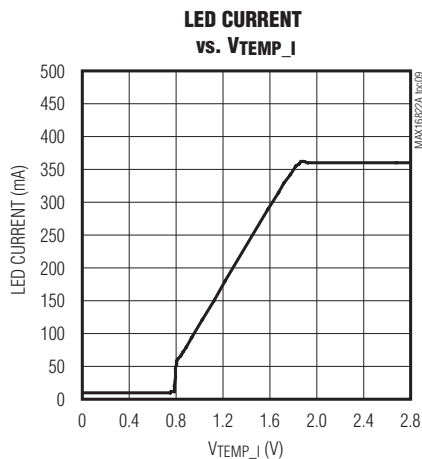
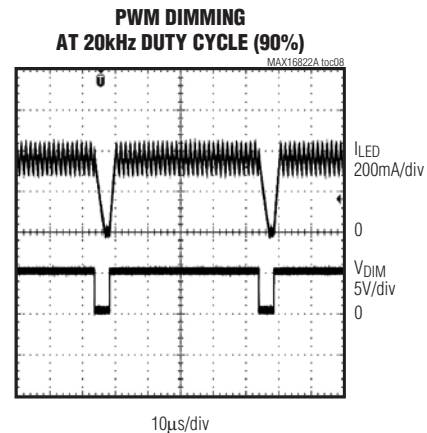
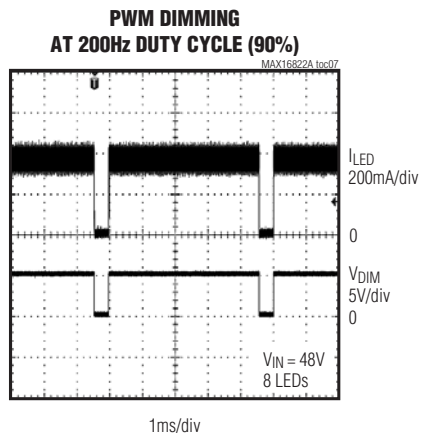
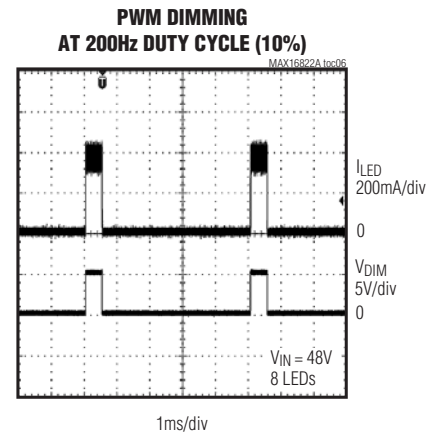
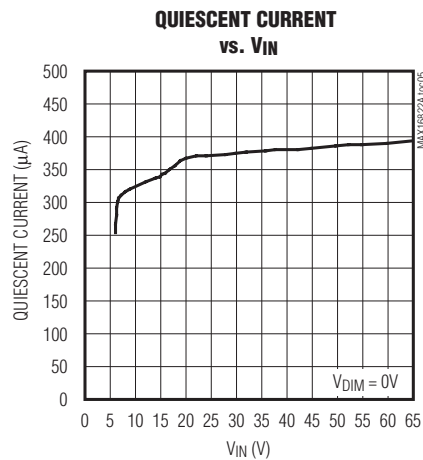
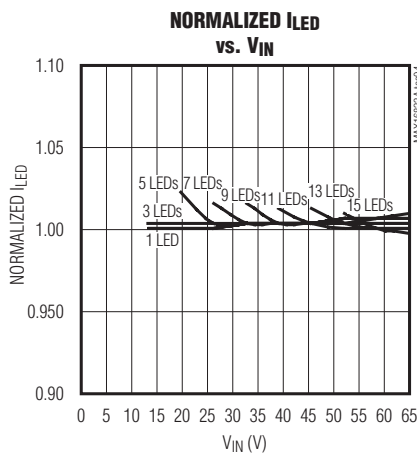
| PARAMETER                                 | SYMBOL               | CONDITIONS                                                                                 | MIN | TYP  | MAX  | UNITS |
|-------------------------------------------|----------------------|--------------------------------------------------------------------------------------------|-----|------|------|-------|
| <b>INTERNAL MOSFET</b>                    |                      |                                                                                            |     |      |      |       |
| Drain-to-Source Resistance                | R <sub>DS(on)</sub>  | V <sub>IN</sub> = V <sub>DIM</sub> = 24V, V <sub>CS</sub> = 23.9V, I <sub>LX</sub> = 350mA |     | 0.85 | 1.7  | Ω     |
|                                           |                      | V <sub>IN</sub> = V <sub>DIM</sub> = 6.0V, V <sub>CS</sub> = 5.9V, I <sub>LX</sub> = 350mA |     | 1    | 2    |       |
| LX Leakage Current                        | I <sub>LX_LEAK</sub> | V <sub>DIM</sub> = 0V, V <sub>LX</sub> = 65V                                               |     |      | 10   | μA    |
| <b>DIM INPUT</b>                          |                      |                                                                                            |     |      |      |       |
| DIM Input-Voltage High                    | V <sub>IH</sub>      | V <sub>IN</sub> - V <sub>CS</sub> = 100mV                                                  | 2.8 |      |      | V     |
| DIM Input-Voltage Low                     | V <sub>IL</sub>      | V <sub>CS</sub> - V <sub>IN</sub> = 100mV                                                  |     |      | 0.6  | V     |
| DIM Turn-On Time                          | t <sub>DIM_ON</sub>  | V <sub>DIM</sub> rising edge to V <sub>LX</sub> < 0.5V <sub>IN</sub>                       |     | 200  |      | ns    |
| DIM Input Leakage High                    |                      | V <sub>DIM</sub> = V <sub>IN</sub>                                                         |     |      | 15   | μA    |
| DIM Input Leakage Low                     |                      | V <sub>DIM</sub> = 0V                                                                      | -3  |      | 0    | μA    |
| <b>THERMAL SHUTDOWN</b>                   |                      |                                                                                            |     |      |      |       |
| Thermal-Shutdown Threshold                |                      | Temperature rising                                                                         |     | 165  |      | °C    |
| Thermal-Shutdown Threshold Hysteresis     |                      |                                                                                            |     | 10   |      | °C    |
| <b>THERMAL FOLDBACK</b>                   |                      |                                                                                            |     |      |      |       |
| Thermal-Foldback Enable Threshold Voltage | V <sub>TFB_ON</sub>  | V <sub>DIM</sub> = 5V                                                                      | 1.9 | 2.0  | 2.12 | V     |
| Thermal-Foldback Slope                    | FBSLOPE              | V <sub>DIM</sub> = 5V                                                                      |     | 0.75 |      | 1/V   |
| TEMP_I Output Bias Current                | I <sub>TEMP_I</sub>  |                                                                                            | 25  | 26.5 | 28   | μA    |

## Typical Operating Characteristics

(V<sub>IN</sub> = V<sub>DIM</sub> = 48V, C<sub>VCC</sub> = 1μF, R<sub>SENSE</sub> = 0.62Ω, L = 220μH (connected between IN and CS). Typical values are at T<sub>A</sub> = +25°C, unless otherwise noted.)

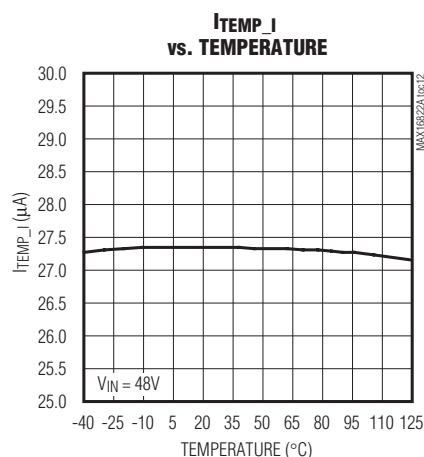
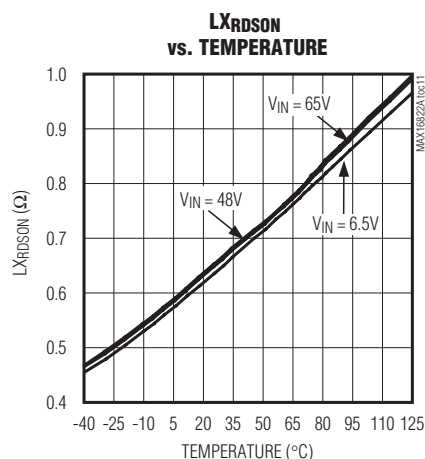
## Typical Operating Characteristics (continued)

( $V_{IN} = V_{DIM} = 48V$ ,  $C_{VCC} = 1\mu F$ ,  $R_{SENSE} = 0.62\Omega$ ,  $L = 220\mu H$  (connected between IN and CS). Typical values are at  $T_A = +25^\circ C$ , unless otherwise noted.)



## Typical Operating Characteristics (continued)

( $V_{IN} = V_{DIM} = 48V$ ,  $C_{VCC} = 1\mu F$ ,  $R_{SENSE} = 0.62\Omega$ ,  $L = 220\mu H$  (connected between IN and CS). Typical values are at  $T_A = +25^\circ C$ , unless otherwise noted.)



## Pin Description

| PIN  | NAME   | FUNCTION                                                                                                                                                                                  |
|------|--------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 1    | CS     | Current-Sense Input. Connect a resistor between IN and CS to program the LED current.                                                                                                     |
| 2    | IN     | Positive Supply Voltage Input. Bypass with a 1μF or higher value capacitor to GND.                                                                                                        |
| 3    | GND    | Ground                                                                                                                                                                                    |
| 4    | PGND   | Power Ground                                                                                                                                                                              |
| 5, 6 | LX     | Switching Node                                                                                                                                                                            |
| 7    | DIM    | Logic-Level Dimming Input. Drive DIM low to turn off the current regulator. Drive DIM high to enable the current regulator.                                                               |
| 8    | TEMP_I | Thermal Foldback Control and Linear Input. Bypass with a 0.01μF capacitor to GND if thermal foldback or analog dimming is used. See the <i>Thermal Foldback</i> section for more details. |

## Detailed Description

The MAX16822A/MAX16822B are step-down, constant-current, high-brightness LED (HB LED) drivers. These devices operate from a +6.5V to +65V input-voltage range. The maximum output current is 500mA, if the part is used at temperatures up to +105°C, or 350mA, if it is used up to +125°C. A high-side current-sense resistor sets the output current and a dedicated PWM

dimming input enables pulsed LED dimming over a wide range of brightness levels.

A high-side current-sensing scheme and an on-board current-setting circuitry minimize the number of external components while delivering LED current with ±3% accuracy, using a 1% sense resistor. See Figure 1 for an internal block diagram.

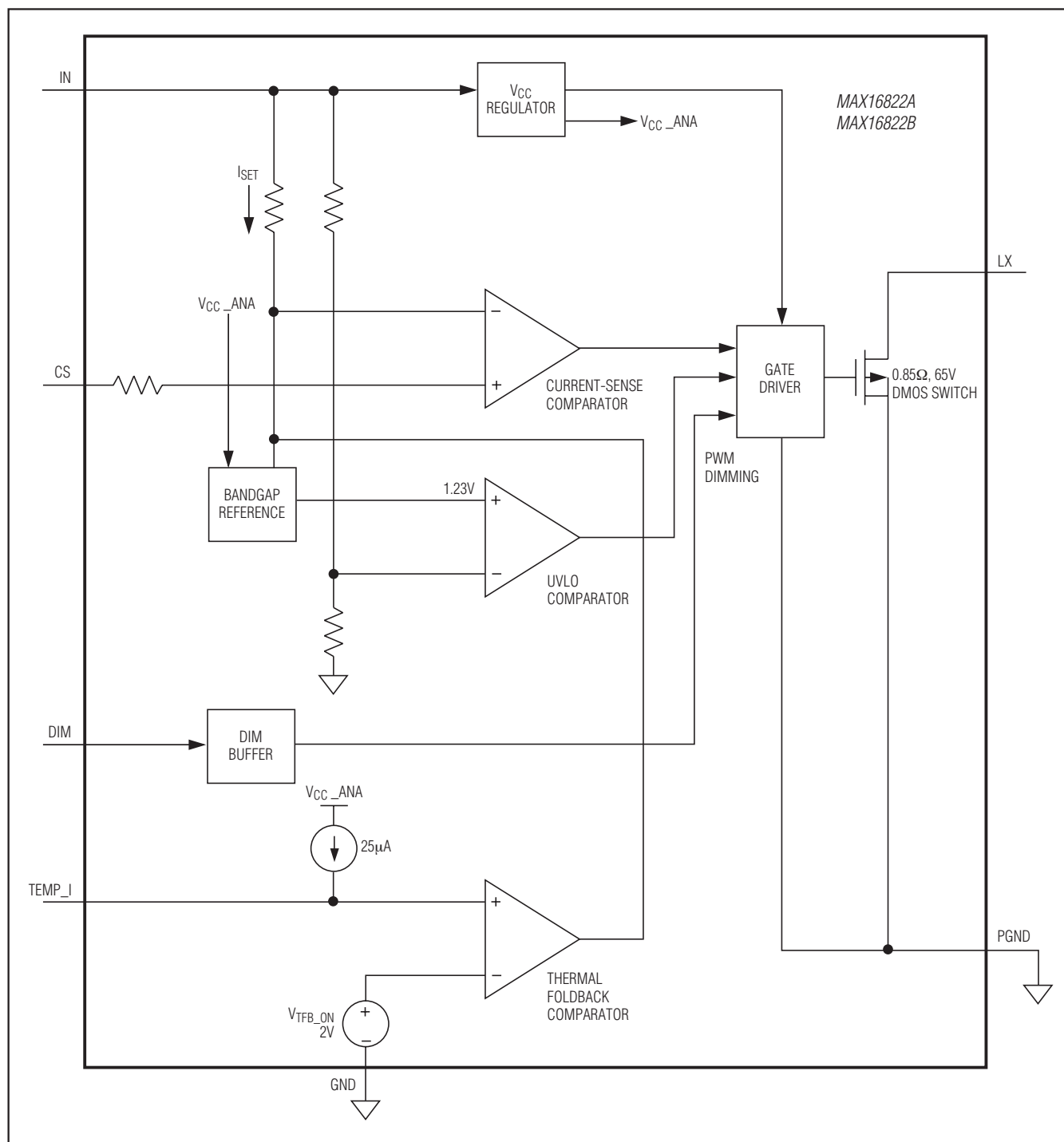


Figure 1. Internal Block Diagram

**Undervoltage Lockout (UVLO)**

The MAX16822A/MAX16822B include UVLO with 500mV hysteresis. The internal MOSFET turns off when  $V_{IN}$  falls below 5.5V to 6.0V.

**DIM Input**

LED dimming is achieved by applying a PWM signal at DIM. A logic level below 0.6V at DIM forces the MAX16822A/MAX16822B's output low, thus turning off the LED current. To turn the LED current on, the logic level at DIM must be greater than 2.8V.

**Thermal Shutdown**

The MAX16822A/MAX16822B thermal-shutdown feature turns off the LX driver when the junction temperature exceeds +165°C. The LX driver turns back on when the junction temperature drops 10°C below the shutdown-temperature threshold.

**Analog Dimming**

The MAX16822A/MAX16822B offer an analog dimming feature that reduces the output current when the voltage at TEMP\_I is below the internal 2V threshold voltage. The MAX16822A/MAX16822B achieve analog dimming by either an external DC voltage source connected between TEMP\_I and ground or by a voltage on a resistor connected across TEMP\_I and ground induced by an internal current source of 25µA. When the voltage at TEMP\_I is below the internal 2V threshold limit, the MAX16822A/MAX16822B reduce the LED current. Use the following formula to set the analog dimming current.

$$I_{TF}(A) = I_{LED}(A) \times \left[ 1 - FB_{SLOPE} \left( \frac{1}{V} \right) \times (V_{TFB\_ON} - V_{AD})(V) \right]$$

where  $V_{TFB\_ON} = 2V$  and  $FB_{SLOPE} = 0.75$  are obtained from the *Electrical Characteristics* table and  $V_{AD}$  is the voltage at TEMP\_I.

**Thermal Foldback**

The MAX16822A/MAX16822B also include a thermal-foldback feature that reduces the output current when the temperature of the LED string exceeds a specified temperature point. These devices enter thermal-foldback mode when the voltage drop on the NTC thermistor, thermally attached to the LEDs and electrically connected between TEMP\_I and ground, drops below the internal 2V threshold limit.

**Applications Information****Selecting  $R_{SENSE}$  to Set LED Current**

The LED current is programmed with a current-sense resistor connected between IN and CS. Use the equation below to calculate the value of this resistor:

$$R_{SENSE}(\Omega) = \frac{1}{2} \frac{(V_{SNSHI} + V_{SNSLO})(V)}{I_{LED}(A)}$$

where  $V_{SNSHI}$  is the sense voltage threshold high and  $V_{SNSLO}$  is sense voltage threshold low (see the *Electrical Characteristics* table for values).

**Current-Regulator Operation**

The MAX16822A/MAX16822B regulate the LED current using a comparator with hysteresis (see Figure 2). As the current through the inductor ramps up and the voltage across the sense resistor reaches the upper threshold, the internal MOSFET turns off. The internal MOSFET turns on again when the inductor current ramps down through the freewheeling diode until the voltage across the sense resistor equals the lower threshold. Use the following equation to determine the operating frequency:

$$f_{SW} = \frac{(V_{IN} - nV_{LED}) \times nV_{LED} \times R_{SENSE}}{V_{IN} \times \Delta V \times L}$$

where  $n$  is the number of LEDs,  $V_{LED}$  is the forward voltage drop of 1 LED, and  $\Delta V = (V_{SNSHI} - V_{SNSLO})$ .

**Inductor Selection**

The MAX16822A/MAX16822B operate up to a switching frequency of 2MHz. For space-sensitive applications, the high switching frequency allows the size of the inductor to be reduced. Use the following formula to calculate an approximate inductor value and use the closest standard value:

$$L(\text{approx.}) = \frac{(V_{IN} - nV_{LED}) \times nV_{LED} \times R_{SENSE}}{V_{IN} \times \Delta V \times f_{SW}}$$

For component selection, use the MAX16822A/B Design Tool available at: [www.maximintegrated.com/MAX16822-software](http://www.maximintegrated.com/MAX16822-software).

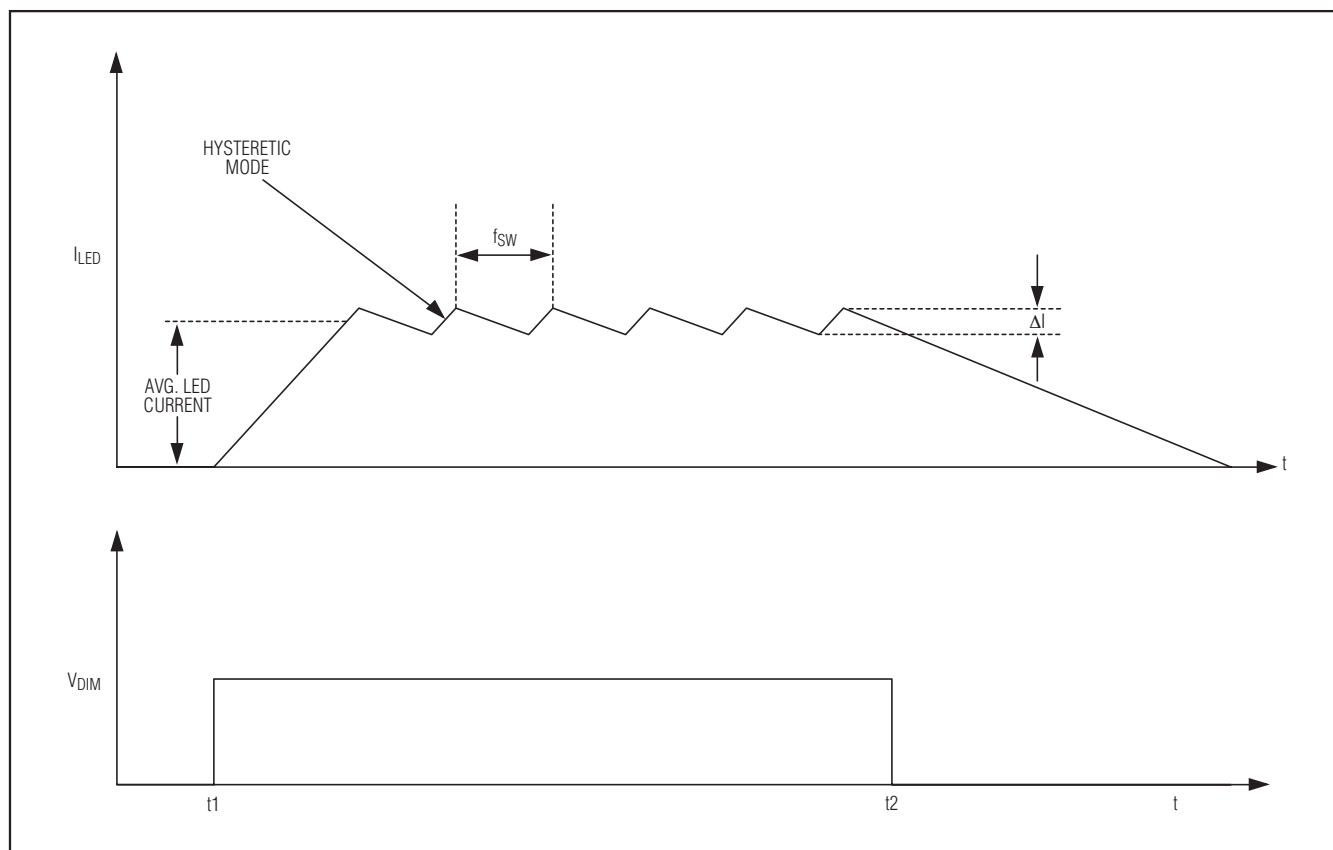


Figure 2. Current-Regulator Operation

### Freewheeling-Diode Selection

For stability and best efficiency, a low forward-voltage drop diode with fast reverse-recovery time and low capacitance is recommended. A Schottky diode is a good choice as long as its breakdown voltage is high enough to withstand the maximum operating voltage.

### PCB Layout Guidelines

Careful PCB layout is critical to achieve low switching losses and stable operation. Use a multilayer board whenever possible for better noise immunity. Minimize ground noise by connecting high-current ground returns, the input bypass-capacitor ground lead, and

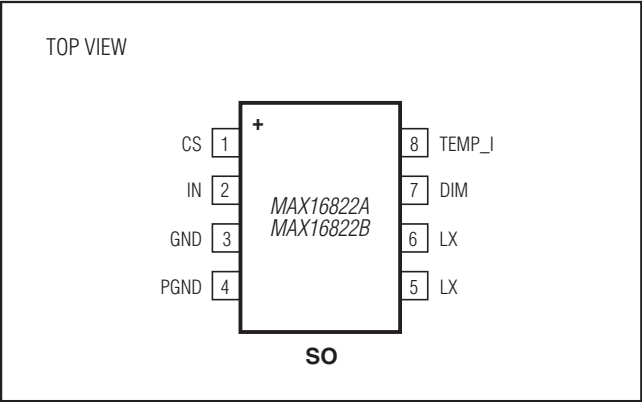
the output-filter ground lead to a single point (star ground configuration). In normal operation, there are two power loops. One is formed when the internal MOSFET is on and the high current flows through IN, R<sub>SENSE</sub>, LED load, the inductor, the internal MOSFET, and GND. The other loop is formed when the internal MOSFET is off and the high-current circulates through R<sub>SENSE</sub>, LED load, the inductor, and the freewheeling diode. Minimize each loop area to reduce noise interaction.

Place R<sub>SENSE</sub> as close as possible to CS and IN. For better noise immunity, a Kelvin connection between CS and R<sub>SENSE</sub> is strongly recommended.

# MAX16822A/MAX16822B

# 2MHz, High-Brightness LED Drivers with Integrated MOSFET and High-Side Current Sense

## Pin Configuration



## Chip Information

PROCESS: BiCMOS

## Package Information

For the latest package outline information and land patterns (footprints), go to [www.maximintegrated.com/packages](http://www.maximintegrated.com/packages). Note that a “+”, “#”, or “-” in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

| PACKAGE TYPE | PACKAGE CODE | DOCUMENT NO.            |
|--------------|--------------|-------------------------|
| 8 SO         | S8-2         | <a href="#">21-0041</a> |

## Revision History

| REVISION<br>NUMBER | REVISION<br>DATE | DESCRIPTION                                                                                                                | PAGES<br>CHANGED |
|--------------------|------------------|----------------------------------------------------------------------------------------------------------------------------|------------------|
| 0                  | 5/08             | Initial release                                                                                                            | —                |
| 1                  | 6/08             | Updated <i>Ordering Information</i> table to release MAX16822B.                                                            | 1                |
| 2                  | 5/09             | Revised <i>General Description</i> , <i>Features</i> , <i>Absolute Maximum Ratings</i> , and <i>Detailed Description</i> . | 1, 2, 5          |
| 3                  | 1/10             | Added <i>V</i> part number.                                                                                                | 1                |
| 4                  | 2/15             | Updated <i>Benefits and Features</i> section                                                                               | 1                |

For pricing, delivery, and ordering information, please contact Maxim Direct at 1-888-629-4642, or visit Maxim Integrated's website at [www.maximintegrated.com](http://www.maximintegrated.com).

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